

**N-Channel High Density Trench MOSFET (20V, 3.5A)****PRODUCT SUMMARY**

V_{DSS}	I_D	$R_{DS(on)}$ (mΩ) Tpy.
20V	3.5A	46 @ VGS = 4.0V, ID=2.8A
		65 @ VGS = 2.5V, ID=1A

Features

- Super high dense cell trench design for low RDS(on)
- Advanced Trench Process Technology
- SOT-23 package
- Lead (Pb)-free and halogen-free

	EN2302 Pin Assignment & Symbol 3-Lead Plastic SOT-23 Pin 1: Gate Pin 2: Source Pin3: Drain	
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Absolute Maximum Ratings ($T_A=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current (Continuous)	3.5	A
I_{DM}	Drain Current (Pulsed) ^a	14	A
P_D	Total Power Dissipation @ $T_A=25^\circ\text{C}$	1	W
I_S	Maximum Diode Forward Current	1.2	A
T_j, T_{stg}	Operating Junction and Storage Temperature Range	-55 to +150	°C
R_{QJA}	Thermal Resistance Junction to Ambient (PCB mounted) ^b	140	°C/W

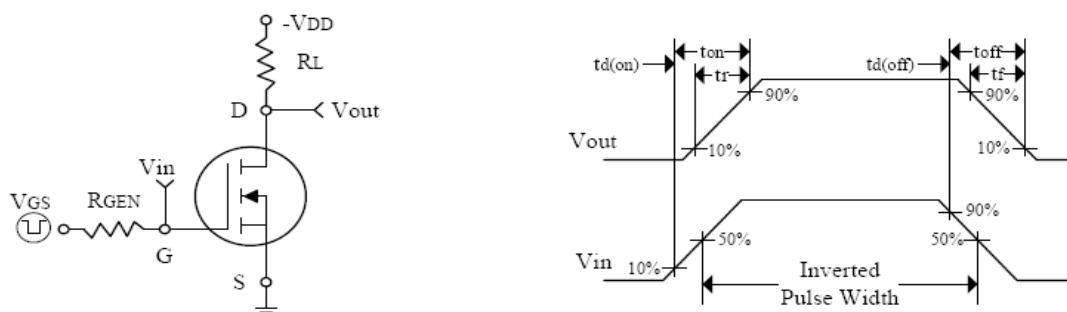
a: Repetitive Rating: Pulse width limited by the maximum junction temperature.

b: 1-in² 2oz Cu PCB board

Electrical Characteristics ($T_A=25^\circ\text{C}$, unless otherwise noted)

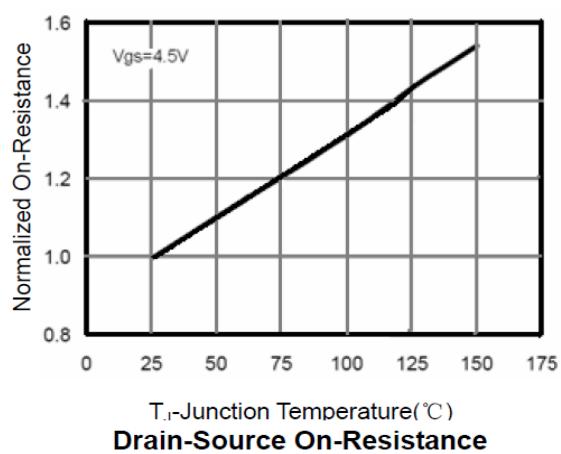
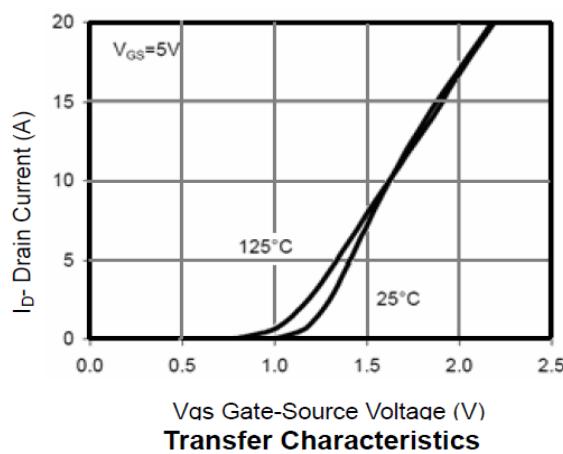
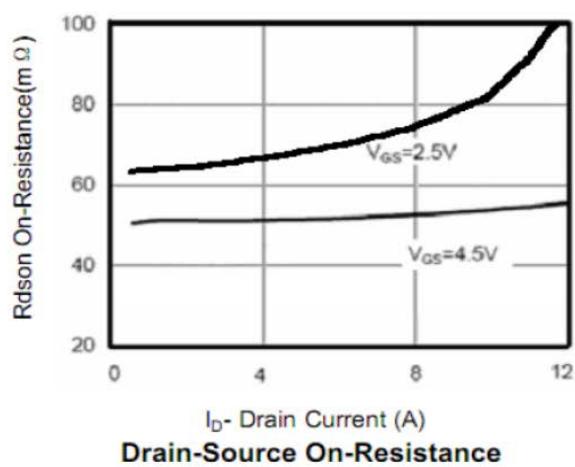
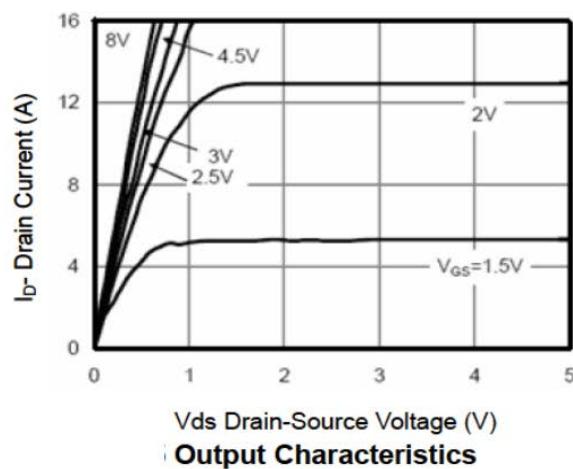
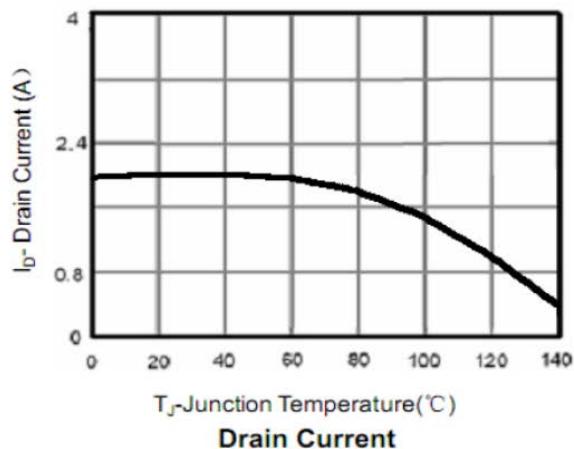
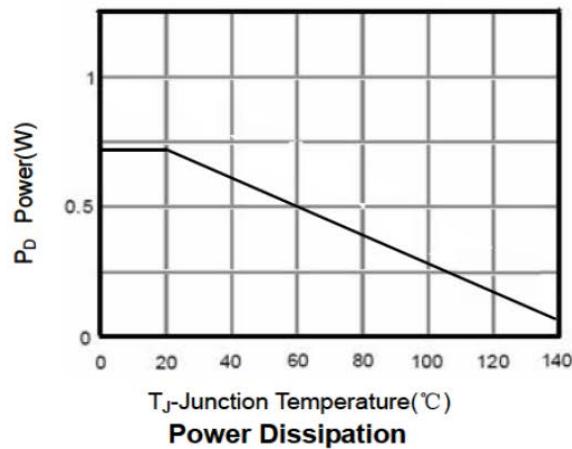
Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
• Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
• On Characteristics						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.4	0.65	1.0	V
$R_{\text{DS(on)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=2.8\text{A}$	-	46	55	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=2\text{A}$	-	65	80	
• Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=6\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	350	-	PF
C_{oss}	Output Capacitance		-	110	-	
C_{rss}	Reverse Transfer Capacitance		-	33	-	
• Switching Characteristics						
Q_g	Total Gate Charge	$V_{\text{DS}}=6\text{V}, I_{\text{D}}=5.4\text{A}, V_{\text{GS}}=4.5\text{V}$	-	4.6	-	nC
Q_{gs}	Gate-Source Charge		-	0.7	-	
Q_{gd}	Gate-Drain Charge		-	1.4	-	
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-6\text{V}, R_{\text{L}}=6\Omega, I_{\text{D}}=1\text{A}, V_{\text{GEN}}=4.5\text{V}, R_{\text{G}}=6\Omega$	-	12	-	nS
t_r	Turn-on Rise Time		-	36	-	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	34	-	
t_f	Turn-off Fall Time		-	5.8	-	
• Drain-Source Diode Characteristics						
V_{SD}	Drain-Source Diode Forward	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1.7\text{A}$	-	-	1.2	V

Note: Pulse Test: Pulse Width $\leq 300\text{us}$, Duty Cycle $\leq 2\%$



Switching Test Circuit and Switching Waveforms

Typical Characteristics Curves (Ta=25°C, unless otherwise note)



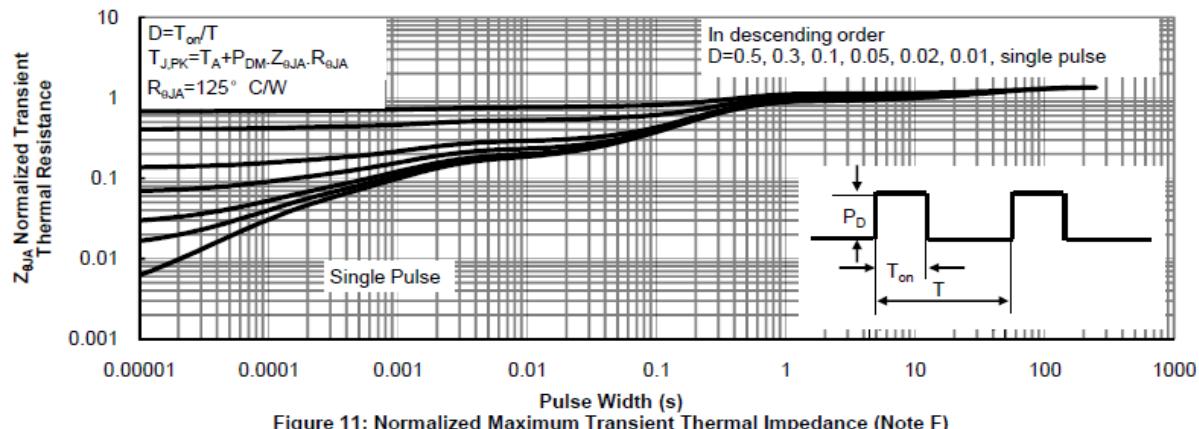
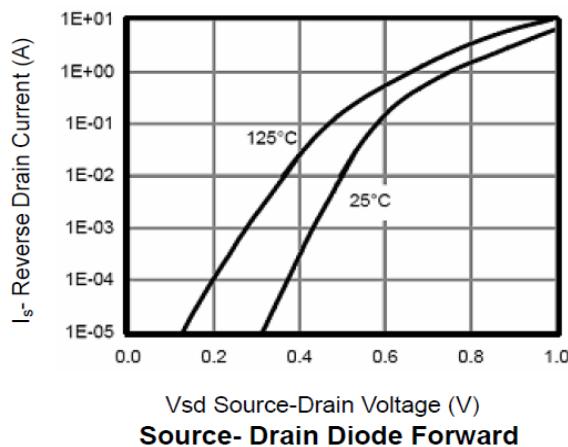
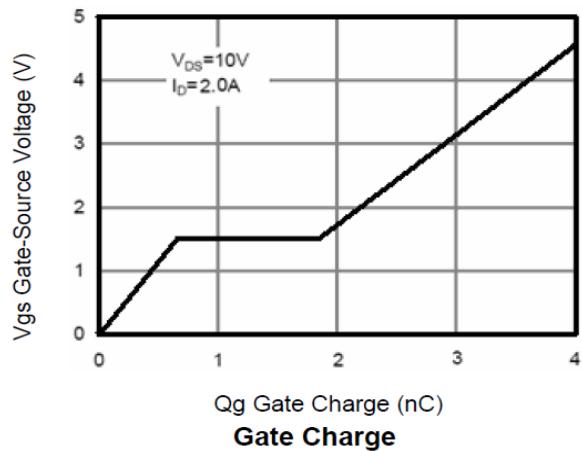
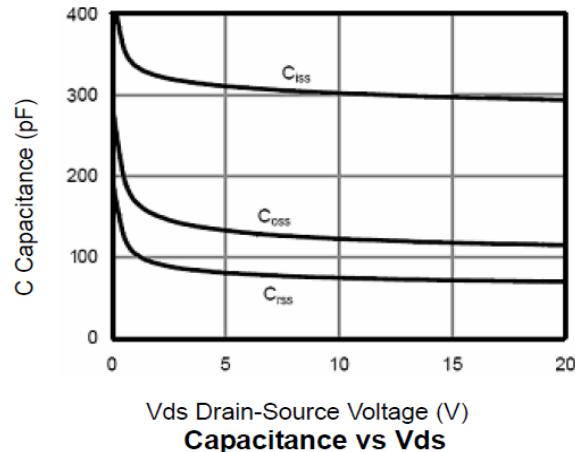
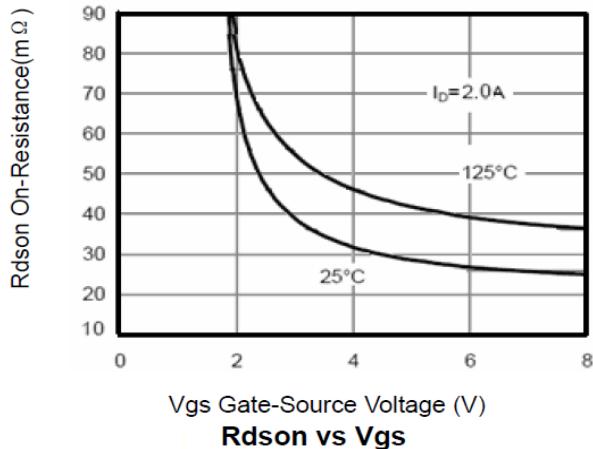
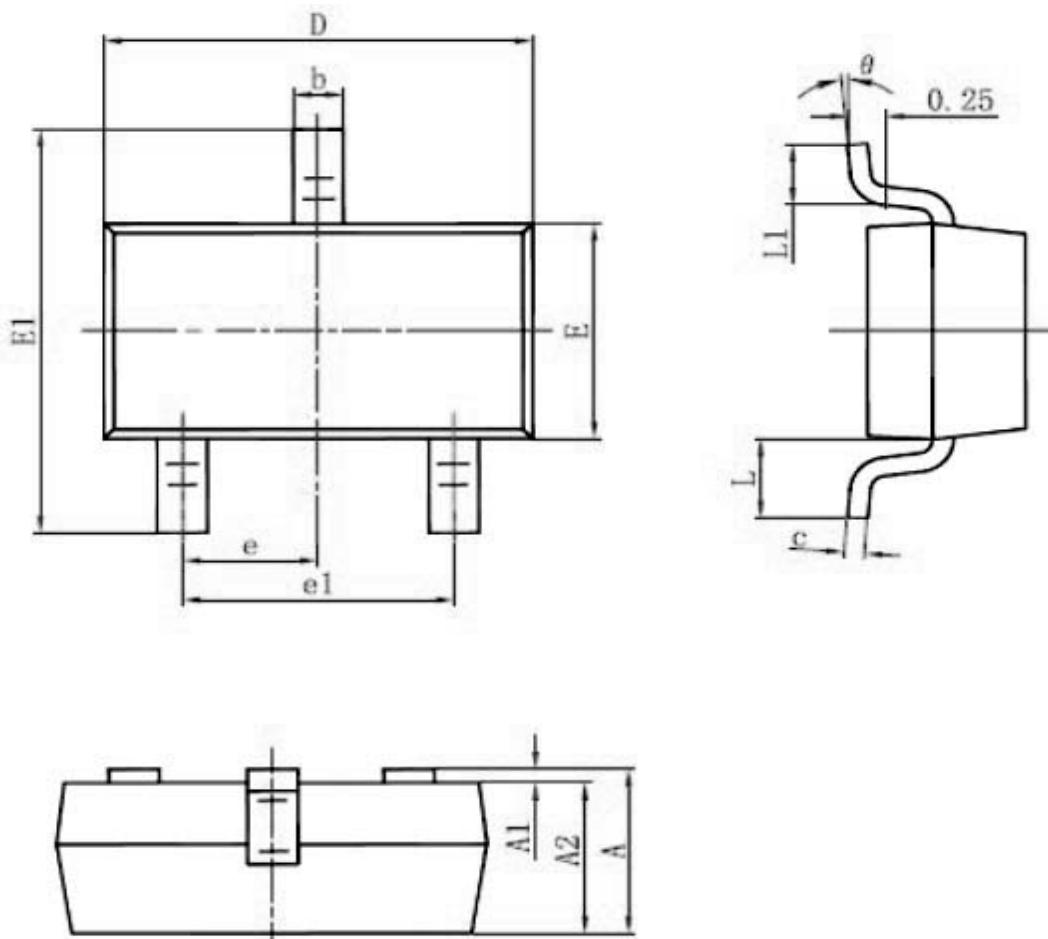


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

SOT-23L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°